

ABSTRACT

A Method For Aligning Contact Pins In An Integrated Circuit Testing**Apparatus**

5 A method of aligning one or more rows of contact pins in an integrated circuit (IC) device testing apparatus that uses structures in bottom plates of the assembly itself to align rows of contact pins. Once a row of contact pins has been inserted into slots located on a socket body in the y-axis, one of the bottom plates is lowered onto the socket body. Some structures on the bottom plate restrict it to movement primarily
10 in the x-axis with respect to the socket body, while other structures allow it to capture all misaligned contact pins and “comb” them into alignment by small adjustments in the x-axis. In this way, the rows of contact pins are aligned as part of the assembly process itself, and no additional tools or equipment are needed.

15 (Figure 7)